

line 9, delete

"BACKGROUND OF THE INVENTION" and insert therefor

- Description of the Background- -.

Page 3, line 31, delete "EMBODIMENT" and insert therefor - - EMBODIMENTS- -.

IN THE CLAIMS

Claim 1, line 1, delete "Substrate" and insert therefor - - A substrate- -.

Claims 2-13, line, delete "Substrate" and insert therefor - - The substrate- -.

Claim 14, line 1, delete "Security" and insert therefor - - A security- -.

Claim 15, line 1, delete "Security" and insert therefor - - A security- -.

Claim 16, line 1, delete "Security" and insert therefor - - A security- -.

Claim 17, line 1, delete "Optically" and insert therefor - - An optically- -.

Please add the following new Claims:

- -18. The substrate according to Claim 1, which further comprises polyimide having polyaniline blocks thereon underneath said semiconductive organic polymer.

19. The substrate according to Claim 1, which further comprises an insulating layer on said semiconductive organic polymer.

20. The substrate according to Claim 1, having an uppermost layer of polyaniline.

21. The substrate according to Claim 1, wherein the paper has a thickness up to 100 μ m.

22. The security paper according to Claim 14, which is a banknote.

23. The security document according to Claim 15, which is a passport.

24. The security document according to Claim 15, which is an identity card.

25. The security document according to Claim 15, which is a security.- -